

# CMS13N06H8-HF

N-Channel  
RoHS Device  
Halogen Free



BVDSS	60V
$I_D@V_{GS}=10V, T_C=25^\circ C$	56A
$I_D@V_{GS}=10V, T_A=25^\circ C$	13.8A
$R_{DS(ON)}@ V_{GS}=10V, I_D=25A$	5.1mΩ(typ)
$R_{DS(ON)}@ V_{GS}=4.5V, I_D=25A$	7.4mΩ(typ)

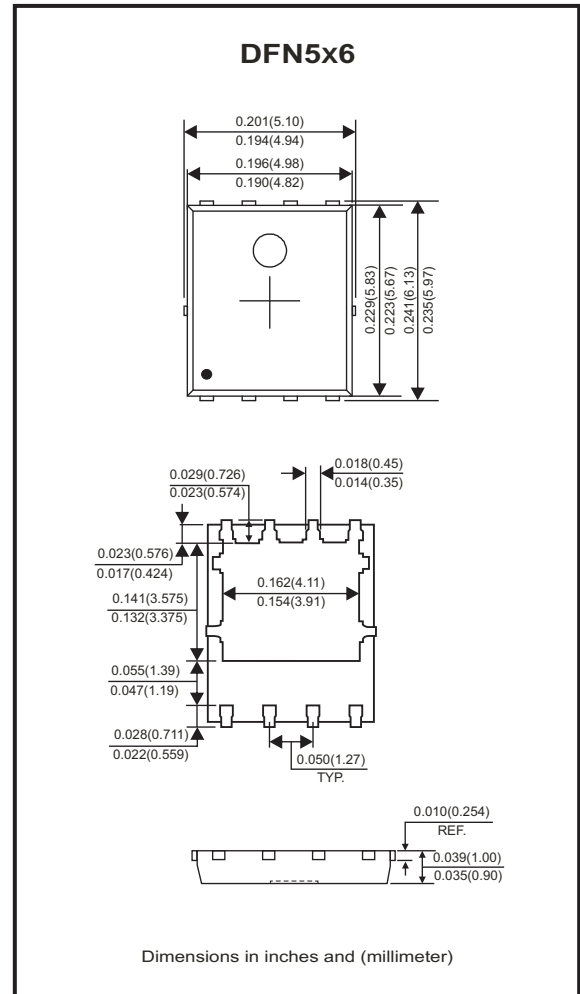
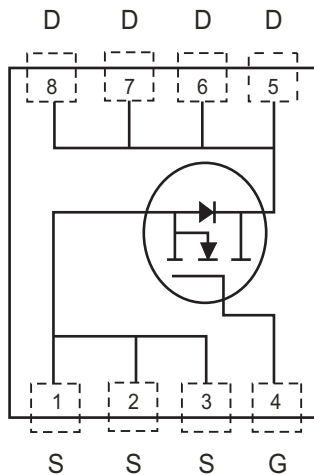
## Features

- Single drive requirement.
- Low On-resistance
- Fast switching characteristic.
- Repetitive avalanche rated

## Mechanical data

- Epoxy : UL 94V-0 rated flame retardant.
- Case : DFN5X6, molded plastic.
- Lead : Pure tin plated.

## Circuit Diagram



## Absolute Maximum Ratings (at Ta=25°C unless otherwise noted)

Parameter	Symbol	10s	Steady State	Unit	
Drain-source voltage	V <sub>DS</sub>	60		V	
Gate-source voltage	V <sub>GS</sub>	±20		V	
Drain current-continuous @ T <sub>c</sub> =25°C, V <sub>GS</sub> =10V (silicon limit) (Note 1)	I <sub>D</sub>	80		A	
Continuous drain current @ T <sub>c</sub> =25°C, V <sub>GS</sub> =10V (package limit) (Note 1)		56		A	
Continuous drain current @ T <sub>c</sub> =100°C, V <sub>GS</sub> =10V (Note 1)		35		A	
Continuous drain current @ T <sub>A</sub> =25°C, V <sub>GS</sub> =10V (Note 2)	I <sub>DSM</sub>	20.8	13.8	A	
Continuous drain current @ T <sub>A</sub> =70°C, V <sub>GS</sub> =10V (Note 2)		16.6	11.0	A	
Continuous drain current @ T <sub>A</sub> =85°C, V <sub>GS</sub> =10V (Note 2)		15.0	9.9	A	
Pulsed drain current (Note3)	I <sub>DM</sub>	224 * 1		A	
Avalanche current (Note3)	I <sub>AS</sub>	40		A	
Avalanche energy @ L=0.1mH, I <sub>D</sub> =40A, V <sub>DD</sub> =30V (Note 2,4)	E <sub>AS</sub>	80		mJ	
Repetitive avalanche energy @ L=0.05mH (Note 3)	E <sub>AR</sub>	10 * 2			
Total power dissipation	P <sub>D</sub>	T <sub>c</sub> =25°C (Note 1)	83		W
		T <sub>c</sub> =100°C (Note 1)	33		
	P <sub>DSM</sub>	T <sub>A</sub> =25°C (Note 2)	5.7	2.5	
		T <sub>A</sub> =70°C (Note 2)	4.0	1.8	
		T <sub>A</sub> =85°C (Note 2)	3.6	1.6	
Operating temperature range	T <sub>J</sub>	-55~+150		°C	
Storage temperature range	T <sub>STG</sub>	-55 to +150		°C	

## Thermal Data

Parameter	Symbol	Typical	Maximum	Unit	
Thermal resistance, junction to ambient (Note 2)	R <sub>θJA</sub>	t ≤ 10s	18	22	°C/W
		Steady state	42	50	°C/W
Thermal resistance junction to case	R <sub>θJC</sub>	1.4	1.5	°C/W	

Notes: 1. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

2. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2 oz. copper, in a still air environment with T<sub>A</sub>=25°C. The power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

3. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C. Ratings are based on low frequency and low duty cycles to keep initial T<sub>J</sub>=25°C

4. 100% tested by conditions of L=0.1mH, I<sub>AS</sub>=10A, V<sub>GS</sub>=10V, V<sub>DD</sub>=30V

## Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
<b>Static</b>						
Drain-source breakdown voltage	$V_{GS} = 0V, I_D = 250\mu A$	$BV_{DSS}$	60			V
Gate-threshold voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(th)}$	1.4		2.6	V
Forward transconductance (Note 1)	$V_{DS} = 10V, I_D = 30A$	$G_{FS}$		30		S
Gate-Source leakage current	$V_{GS} = \pm 20V$	$I_{GSS}$			$\pm 100$	nA
Zero gate voltage drain current	$V_{DS} = 48V, V_{GS} = 0V$	$I_{DSS}$			1	$\mu A$
	$V_{DS} = 48V, V_{GS} = 0V, T_J = 125^\circ C$	$I_{DSS}$			25	
Static drain-source on-resistance (Note 1)	$V_{GS} = 10V, I_D = 25A$	$R_{DS(on)}$		5.1	6.4	m $\Omega$
	$V_{GS} = 4.5V, I_D = 25A$			7.4	9.6	
<b>Dynamic</b>						
Input capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$	$C_{iss}$		1619		pF
Output capacitance		$C_{oss}$		275		
Reverse transfer capacitance		$C_{rss}$		143		
Total gate charge (Note 1,2)	$V_{DS} = 48V, V_{GS} = 10V, I_D = 25A$	$Q_g$		42.8		nC
Gate-source charge (Note 1,2)		$Q_{gs}$		5.8		
Gate-drain charge (Note 1,2)		$Q_{gd}$		15.6		
Turn-on delay time (Note 1,2)	$V_{DS} = 30V, I_D = 1A,$ $V_{GS} = 10V, R_{GS} = 6\Omega$	$t_{d(on)}$		15.2		ns
Turn-on rise time (Note 1,2)		$t_r$		22.4		
Turn-off delay time (Note 1,2)		$t_{d(off)}$		74		
Turn-off fall time (Note 1,2)		$t_f$		36		
Gate resistance	$f = 1MHz$	$R_g$		4		$\Omega$
<b>Source-Drain Diode</b>						
Drain-source diode forward current (Note 1)		$I_s$			56	A
Pulse diode forward current (note3)		$I_{SM}$			224	
Drain-source diode forward voltage (Note 1)	$V_{GS} = 0V, I_s = 25A$	$V_{SD}$		0.82	1.2	V
Body Diode Reverse Recovery Time	$I_F = 25A, dI_F/dt = 100A/\mu s$	$t_{rr}$		18		nS
Body Diode Reverse Recovery Charge		$Q_{rr}$		12		nC

- Notes: 1. Pulse test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$ .  
 2. Independent of operating temperature  
 3. Pulse width limited by maximum junction temperature.

## RATING AND CHARACTERISTIC CURVES (CMS13N06H8-HF)

Fig.1 - Typical Output Characteristics

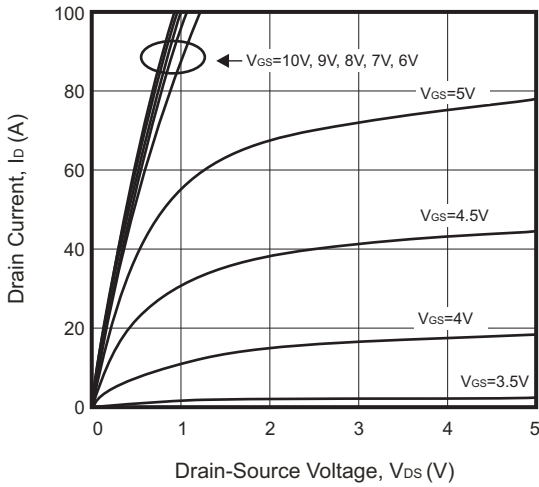


Fig.2 - Static Drain-Source On-State Resistance VS Drain Current

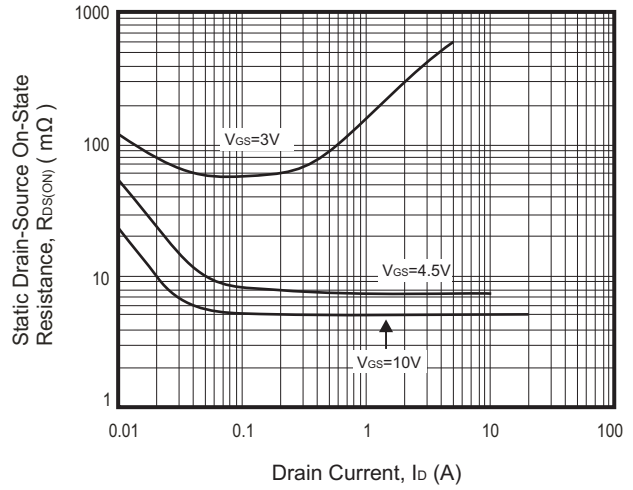


Fig.3 - Static Drain-Source On-State Resistance VS Gate-Source Voltage

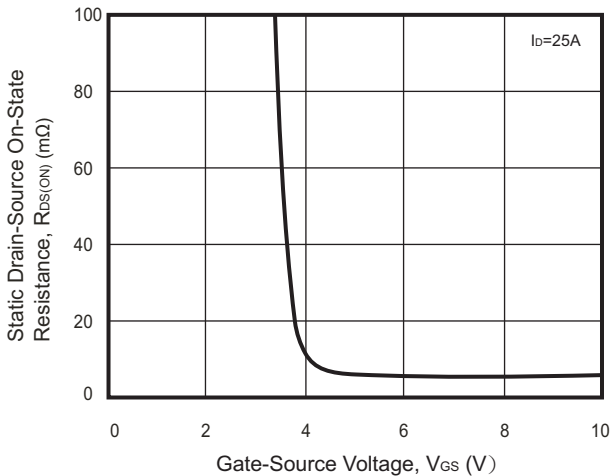


Fig.4 - Capacitance VS Drain-Source Voltage

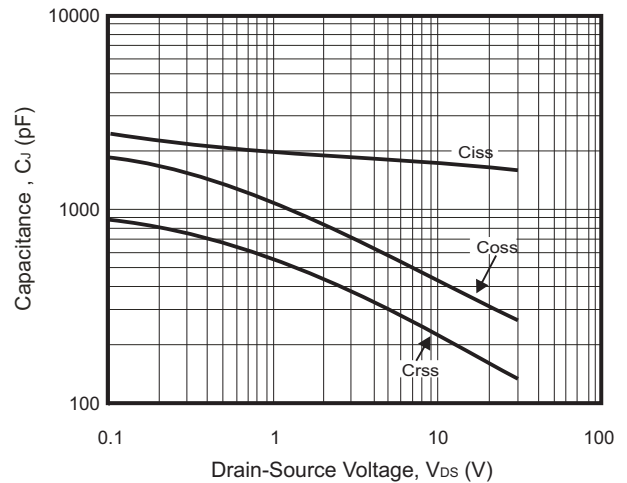


Fig.5 - Forward Transfer Admittance VS Drain Current

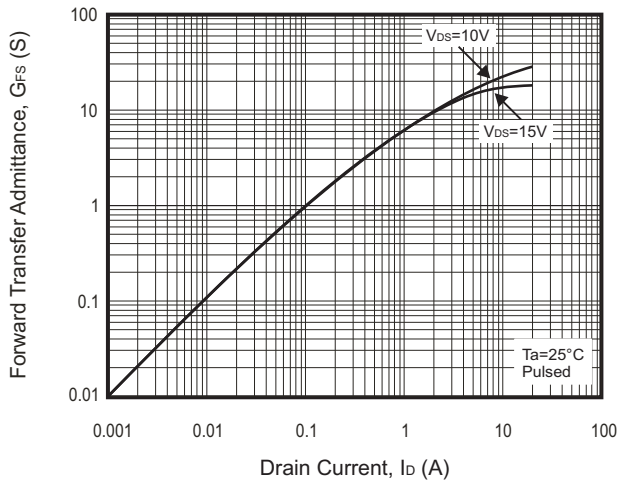
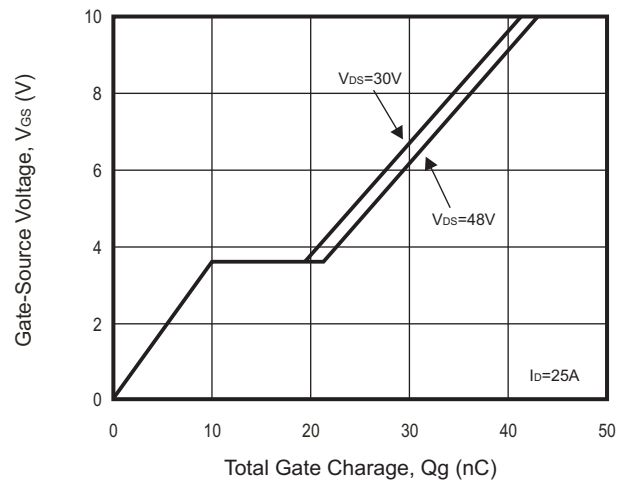
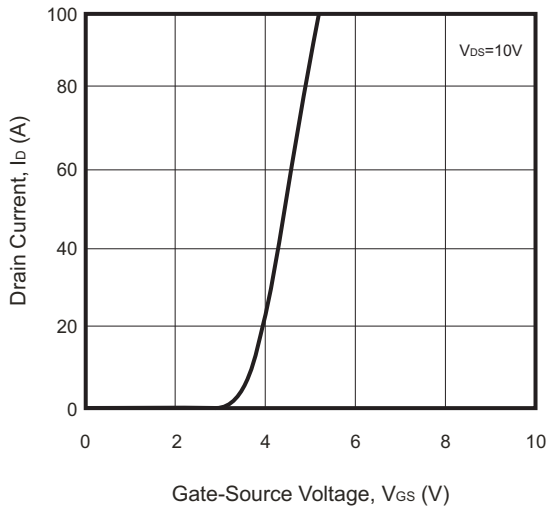


Fig.6 - Gate Charge Characteristics

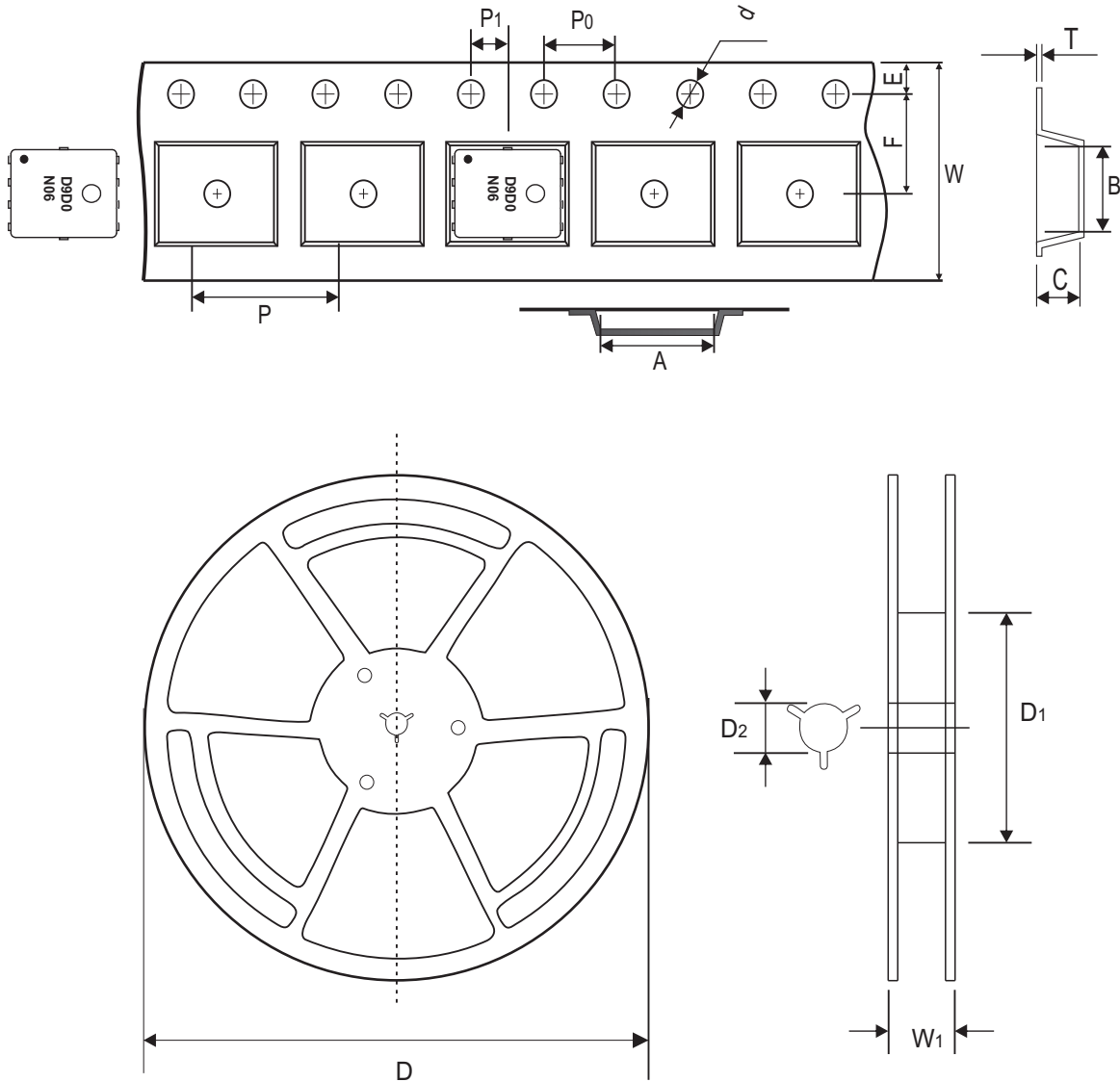


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Fig.7 - Typical Transfer Characteristics



Reel Taping Specification



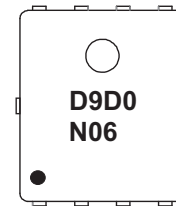
DFN5X6	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	6.30 ± 0.10	5.30 ± 0.10	1.10 ± 0.10	1.50 + 0.10 - 0.00	330.00 ± 1.00	100.00 ± 0.50	13.00 ± 0.20
	(inch)	0.248 ± 0.004	0.209 ± 0.004	0.043 ± 0.004	0.059 + 0.004 - 0.000	12.992 ± 0.039	3.937 ± 0.020	0.512 ± 0.008

DFN5X6	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.25 ± 0.02	12.00 + 0.30 - 0.10	17.60 + 1.00 - 0.00
	(inch)	0.069 ± 0.004	0.217 ± 0.002	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.010 ± 0.001	0.472 + 0.012 - 0.004	0.693 + 0.039 - 0.000

Company reserves the right to improve product design , functions and reliability without notice.

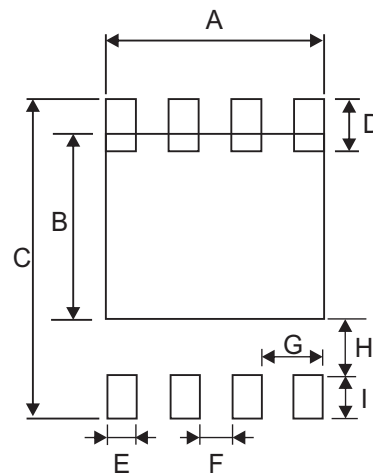
## Marking Code

Part Number	Marking Code
CMS13N06H8-HF	D9D0N06



## Suggested PAD Layout

SIZE	DFN5X6	
	(mm)	(inch)
A	4.42	0.174
B	3.81	0.150
C	6.61	0.260
D	1.02	0.040
E	0.61	0.024
F	0.66	0.026
G	1.27	0.050
H	1.23	0.048
I	0.86	0.034



## Standard Packaging

Case Type	REEL PACK	
	REEL ( pcs )	Reel Size (inch)
DFN5X6	3,000	13